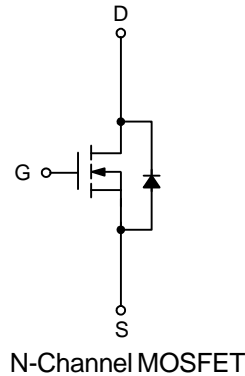
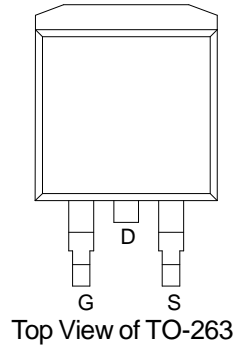


N-Channel Enhancement Mode MOSFET

Features

- 75V/75A ,
 $R_{DS(ON)} = 9.1m\Omega$ (typ.) @ $V_{GS} = 10V$
- Avalanche Rated
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)


Pin Description



Applications

- Power Management for Inverter Systems

Ordering and Marking Information

<p>APM7512N □□-□□ □</p> <div style="margin-left: 20px;"> <p>└─ Assembly Material</p> <p>└─ Handling Code</p> <p>└─ Temperature Range</p> <p>└─ Package Code</p> </div>	<p>Package Code G : TO-263</p> <p>Operating Junction Temperature Range C : -55 to 175 °C</p> <p>Handling Code TR : Tape & Reel</p> <p>Assembly Material L : Lead Free Device G : Halogen and Lead Free Device</p>
<p>APM7512N G : </p>	<p>XXXXX - Date Code</p>

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020C for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage	75	V	
V_{GSS}	Gate-Source Voltage	± 25		
T_J	Maximum Junction Temperature	175	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$	
I_S	Diode Continuous Forward Current	40	A	
I_{DP}	300 μs Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	300*	A
		$T_C=100^\circ\text{C}$	200	
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	75	A
		$T_A=100^\circ\text{C}$	55	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	150	W
		$T_A=100^\circ\text{C}$	75	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1	$^\circ\text{C/W}$	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	45	$^\circ\text{C/W}$	
Drain-Source Avalanche Ratings				
E_{AS}	Avalanche Energy, Single Pulsed	L=2mH	1	J

Note:

* Pulse width limited by safe operating area.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	APM7512NG			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu\text{A}$	75			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			1	μA
					30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	2.5	3.5	4.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$			± 100	nA
$R_{DS(ON)}^a$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=40A$		9.1	12	$\text{m}\Omega$
Diode Characteristics						
V_{SD}^a	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$		0.8	1.3	V
t_{rr}	Reverse Recovery Time	$I_{DS}=40A, dI_{SD}/dt=100A/\mu\text{s}$		70		ns
q_{rr}	Reverse Recovery Charge			193		nC

Electrical Characteristics (T_A = 25°C Unless Otherwise Noted)

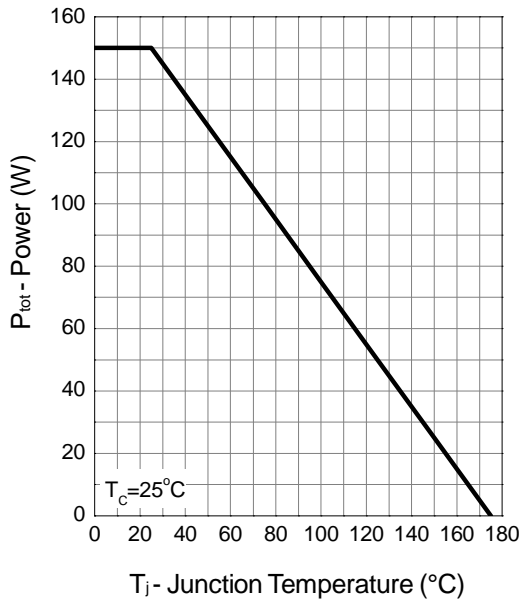
Symbol	Parameter	Test Condition	APM7512NG			Unit
			Min.	Typ.	Max.	
Dynamic Characteristics^b						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.5		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, Frequency=1.0MHz		3740		pF
C _{oss}	Output Capacitance			510		
C _{rss}	Reverse Transfer Capacitance			195		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =35V, R _L =35Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω		25	46	ns
t _r	Turn-on Rise Time			15	28	
t _{d(OFF)}	Turn-off Delay Time			65	118	
t _f	Turn-off Fall Time			34	62	
Gate Charge Characteristics^b						
Q _g	Total Gate Charge	V _{DS} =30V, V _{GS} =10V, I _{DS} =40A		69	97	nC
Q _{gs}	Gate-Source Charge			17.5		
Q _{gd}	Gate-Drain Charge			22		

Notes :

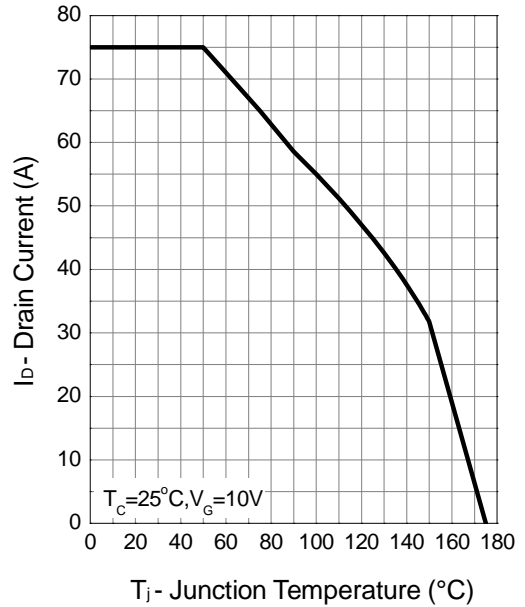
- a : Pulse test ; pulse width ≤ 300μs, duty cycle ≤ 2%.
- b : Guaranteed by design, not subject to production testing.

Typical Characteristics

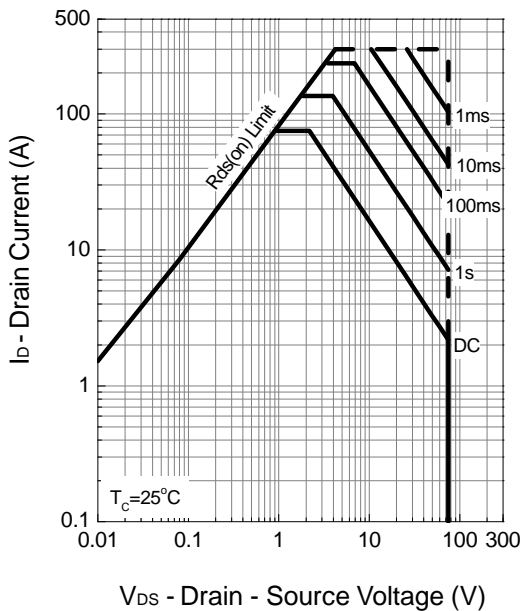
Power Dissipation



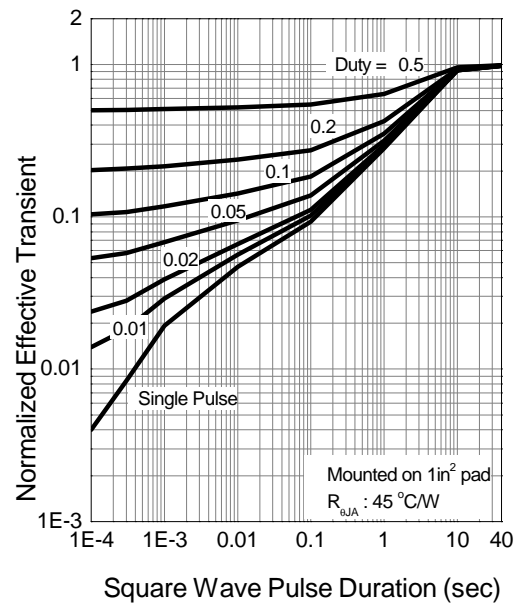
Drain Current



Safe Operation Area

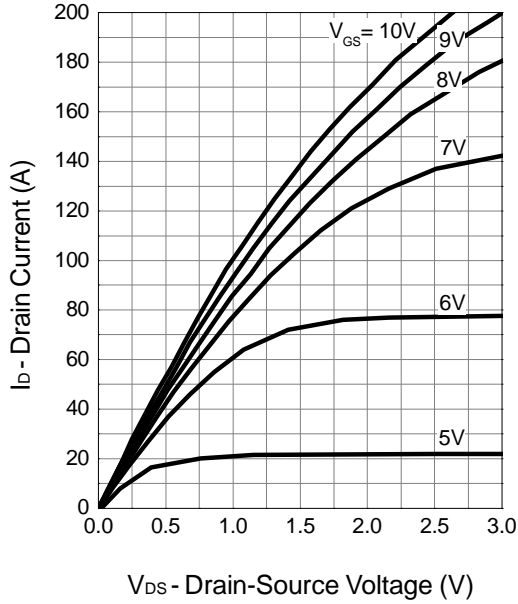


Thermal Transient Impedance

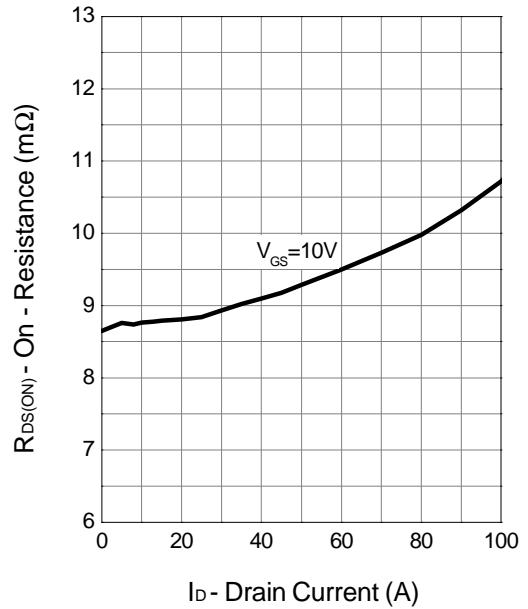


Typical Characteristics (Cont.)

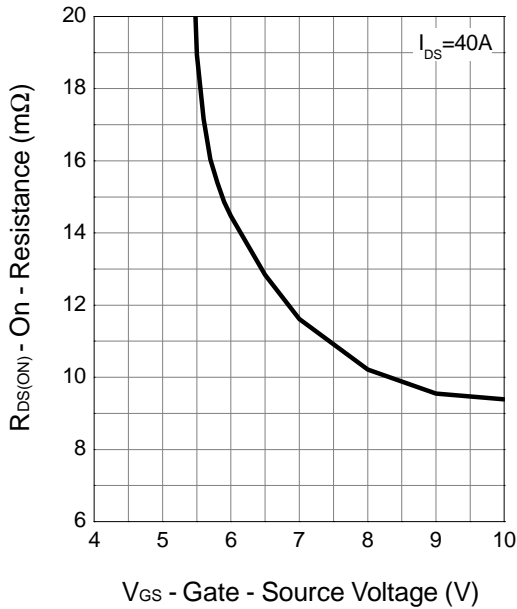
Output Characteristics



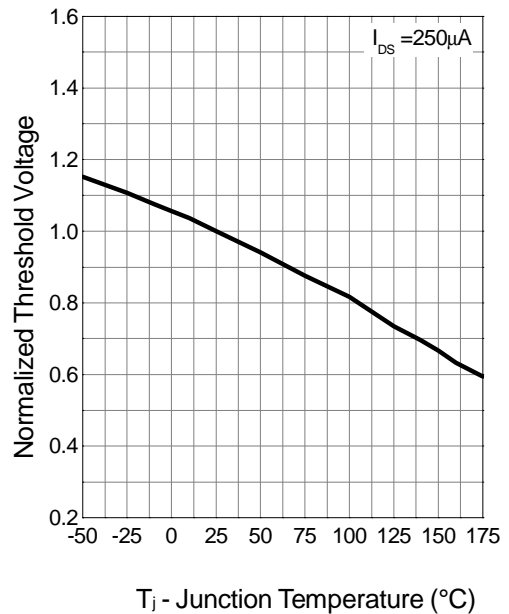
Drain-Source On Resistance



Drain-Source On Resistance

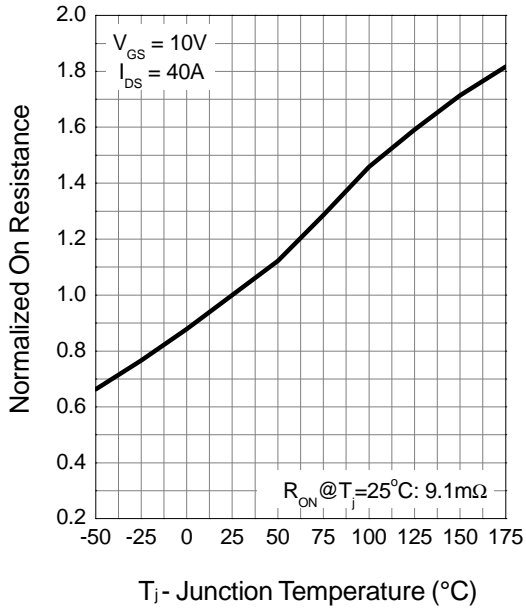


Gate Threshold Voltage

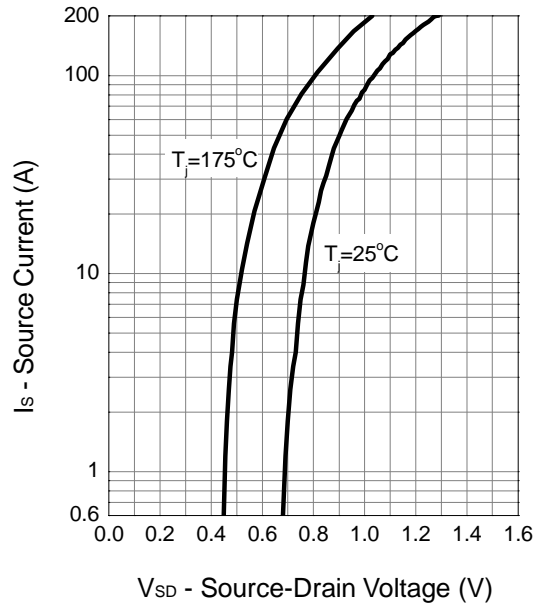


Typical Characteristics (Cont.)

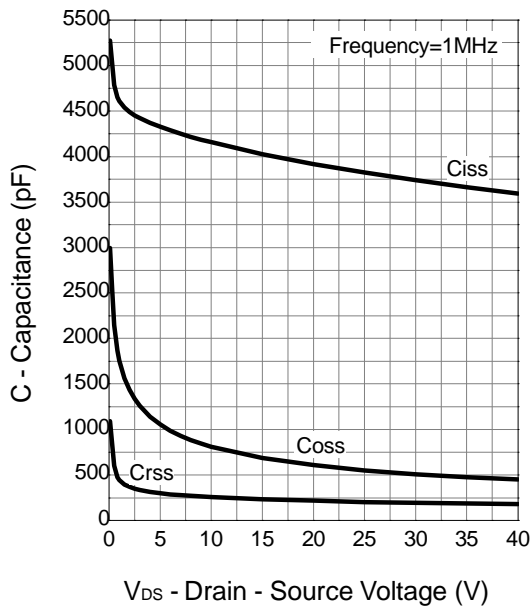
Drain-Source On Resistance



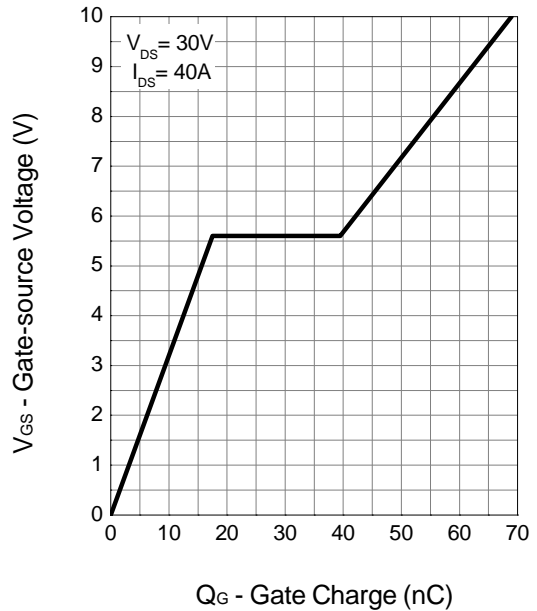
Source-Drain Diode Forward



Capacitance

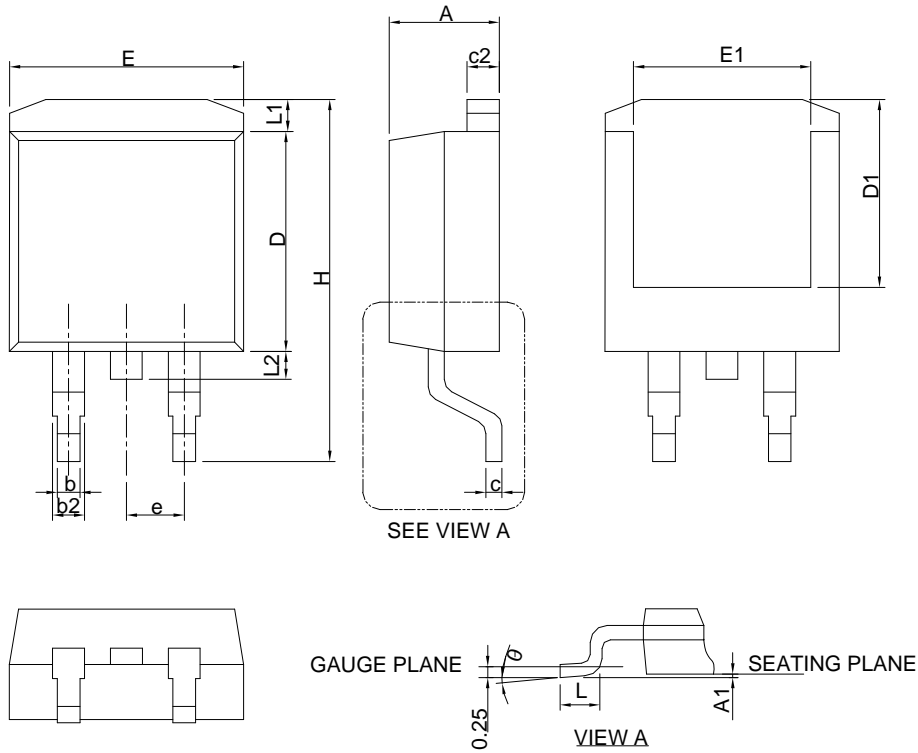


Gate Charge



Package Information

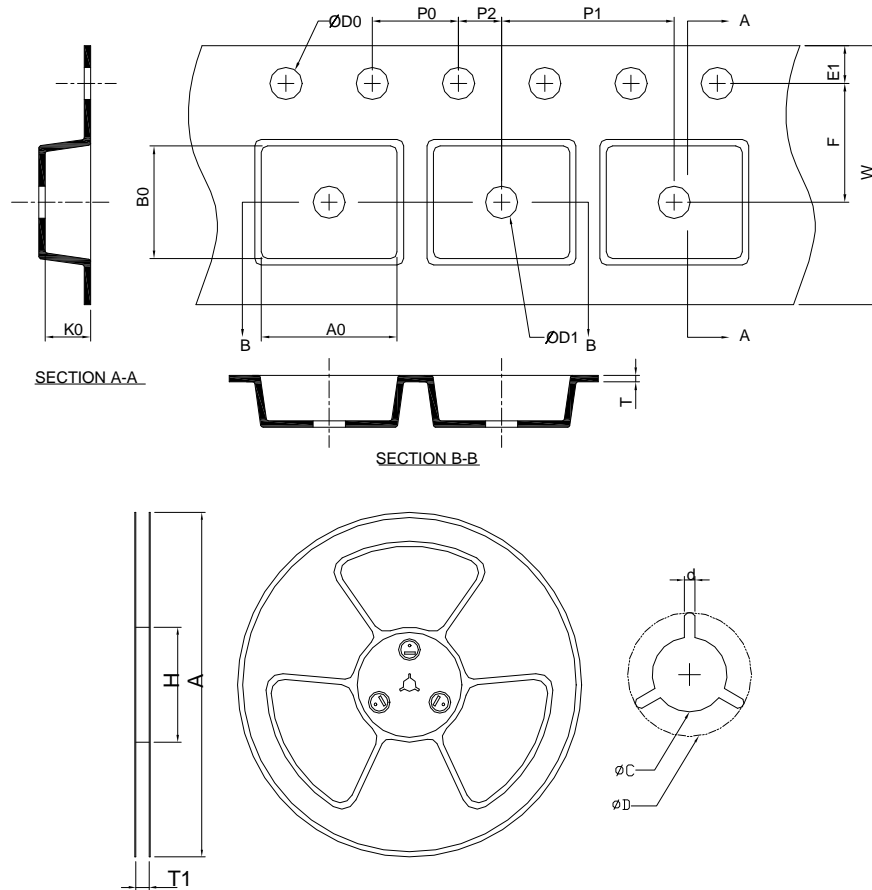
TO-263-3



SYMBOL	TO263			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b2	1.14	1.78	0.045	0.070
c	0.38	0.74	0.015	0.029
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380
D1	6.00	9.00	0.236	0.354
E	9.65	11.43	0.380	0.450
E1	6.22	9.00	0.245	0.354
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1		1.68		0.066
L2		1.78		0.070
θ	0°	8°	0°	8°

Note : Follow JEDEC TO-263 AB.

Carrier Tape & Reel Dimensions

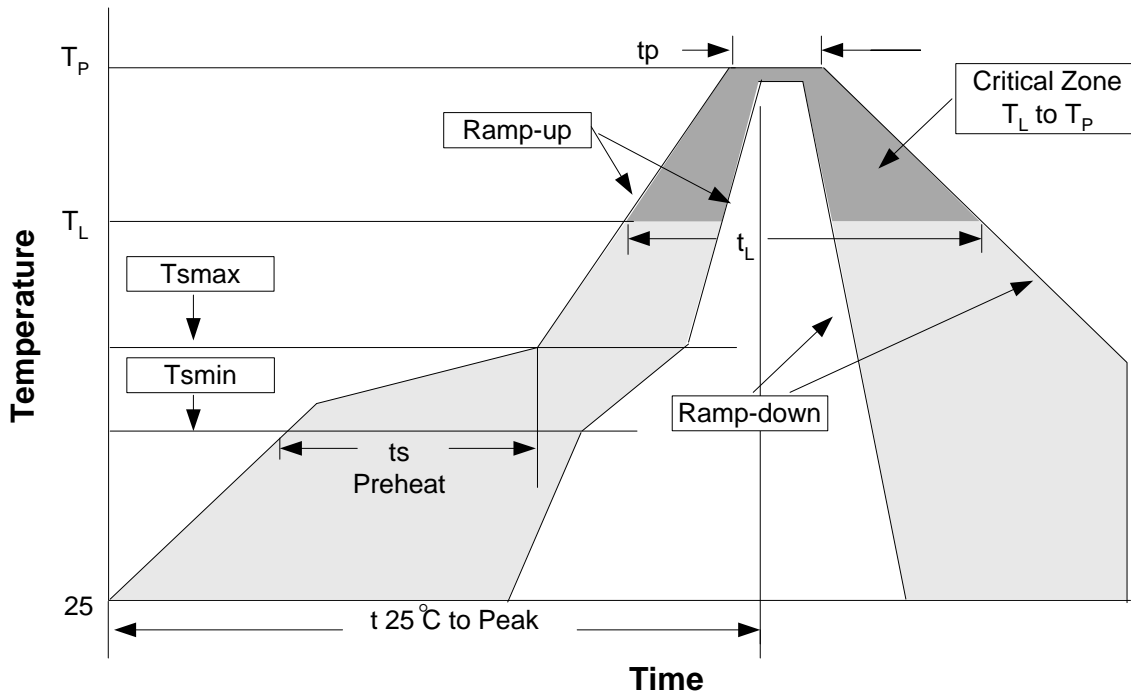


Application	A	H	T1	C	d	D	W	E1	F
TO-263	381.0 ±2.00	60 MIN.	24.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	24.0 ±0.30	1.75 ±0.10	11.5 ±0.10
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 ±0.10	16.0 ±0.10	2.0 ±0.10	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	10.8 ±0.20	16.1 ±0.20	5.2 ±0.20

Devices Per Unit

Package Type	Unit	Quantity
TO-263	Tape & Reel	1000

Reflow Condition (IR/Convection or VPR Reflow)



Reliability Test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 sec
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @125°C
PCT	JESD-22-B, A102	168 Hrs, 100%RH, 121°C
TST	MIL-STD-883D-1011.9	-65°C~150°C, 200 Cycles

Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min (T _{smin})	100°C	150°C
- Temperature Max (T _{smax})	150°C	200°C
- Time (min to max) (t _s)	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T _p)	See table 1	See table 2
Time within 5°C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package. Measured on the body surface.

Classification Reflow Profiles (Cont.)

Table 1. SnPb Eutectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 2. Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 +0°C*	260 +0°C*	260 +0°C*
1.6 mm – 2.5 mm	260 +0°C*	250 +0°C*	245 +0°C*
≥2.5 mm	250 +0°C*	245 +0°C*	245 +0°C*

*Tolerance: The device manufacturer/supplier **shall** assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C) at the rated MSL level.

Customer Service

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